

2.4GHz Loop Chip Antenna



AANI-CH-0070

Request Samples



Check Inventory



1.0 x 0.5 x 0.4 mm
RoHS/RoHS II Compliant
MSL Level = 1

Reflow Profile [JEDEC J-STD-020]

Solder paste: Sn/3.0Ag/0.5Cu

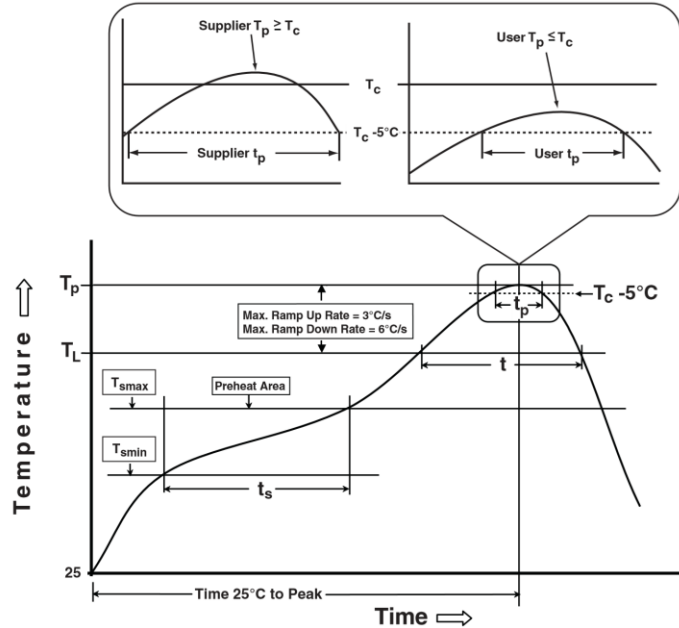


Table 1

SnPb Eutectic Process

Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2

Pb-Free Process

Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6mm - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum (T _{smmin})	100°C	150°C
Temperature maximum (T _{smmax})	150°C	200°C
Time (T _{smmin} to T _{smmax}) (t _s)	60 – 120 sec.	60 – 90 sec.
Average ramp-up rate (T _{smmax} to T _p)	3°C/sec. max	3°C/sec. max
Liquidous temperature (T _L)	183°C	217°C
Time at Liquidous (T _L)	60 – 150 sec.	60 – 150 sec.
Peak package body temperature (T _p)*	See Table 1	See Table 2
Time (T _p)* within 5°C of the specified classification temperature (T _c)	20 sec.	10 sec.
Ramp-down rate (T _p to T _{smmax})	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

*Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

**Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.



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REVISION A: 12-20-24

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